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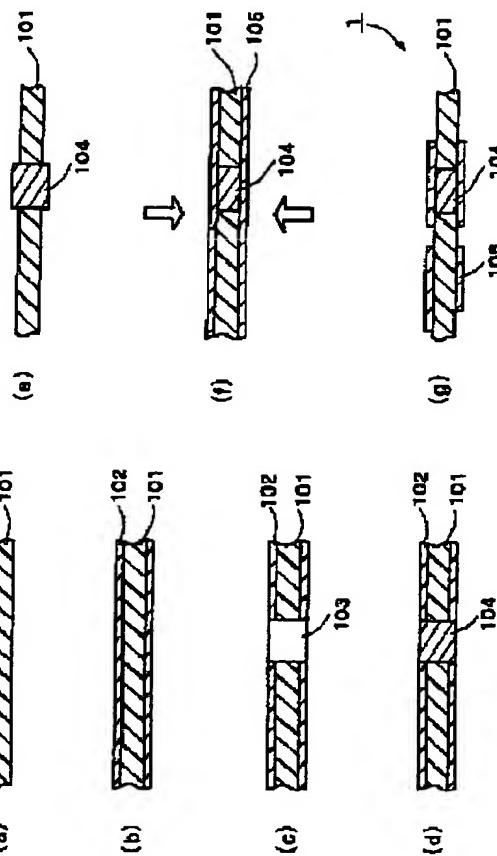
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TITLE : MANUFACTURE OF PRINTED WIRING BOARD, AND MANUFACTURE OF ELECTRONIC PARTS MOUNTING WIRING BOARD



**ABSTRACT :** PROBLEM TO BE SOLVED: To provide a method for manufacturing a printed wiring board which can connect electronic parts with excellent reliability of electric connection.

**SOLUTION:** An insulating board 101, which has a through hole 103 filled with conductive material 104 and is made, being impregnated with thermosetting resin, is prepared (a), and metallic layers 102 are arranged on both sides of the insulating board 101 (b), and the first heat pressurization treatment is performed for the metallic layer 102 and the insulating board 101 for unification (c), and then the second heat pressurization treatment is performed, at a higher temperature than the glass transition temperature after curing of the thermosetting resin and besides at a pressure lower than the first processing pressure, for the united substance (d), whereby each metallic layer 102 is processed into wiring pattern form (e). It is to be desired that the second heat pressurization treatment should be performed in vacuum or inert gas, and as base material, aramide unwoven fabric, and as thermosetting resin, epoxy resin or the like can be used, respectively.

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